IN THE CLAIMS

Claims 2-3 are pending in this application. Please amend claims 2-3 as follows:

1. (Canceled)

2. (Currently Amended) A method for purifying semiconductor nanoparticles, comprising the steps of:

modifying semiconductor nanoparticles with oil-soluble materials for surface modification;

converting the oil-soluble materials for surface modification into water-soluble materials for surface modification at the interface between an organic solvent and water;

shifting the semiconductor nanoparticles from an organic phase to an aqueous phase by the conversion; and then

subjecting the semiconductor nanoparticles, the surfaces of which have been modified with the water-soluble materials for surface modification, to size-selective photoetching, wherein the semiconductor nanoparticles are irradiated with monochromatic light of a wavelength shorter than a wavelength of the semiconductor nanoparticles' absorption edge so that the surface of the semiconductor nanoparticles is dissolved and peeled by the size-selective photoetching, and particle sizes of the semiconductor nanoparticles are regulated and the semiconductor nanoparticles are monodispersed by the dissolution.

3. (Currently Amended) A method for purifying semiconductor nanoparticles, comprising the steps of:

modifying semiconductor nanoparticles with oil-soluble materials for surface modification;

converting the oil-soluble materials for surface modification into water-soluble materials for surface modification at the interface between an organic solvent and water;

shifting the semiconductor nanoparticles from an organic phase to an aqueous phase by the conversion; and then

subjecting the semiconductor nanoparticles, the surfaces of which have been modified with the water-soluble materials for surface modification, to size-selective photoetching, wherein the semiconductor nanoparticles are irradiated with monochromatic light of a wavelength shorter than a wavelength of the semiconductor nanoparticles' absorption edge so that ~~whereby~~ the dissolution caused thereby is utilized to peel the surface of the semiconductor nanoparticles, thereby converting the materials for surface modification.